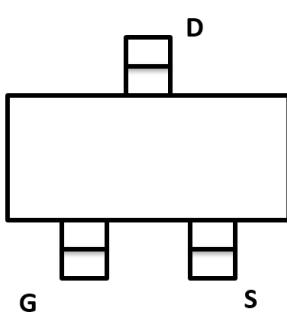
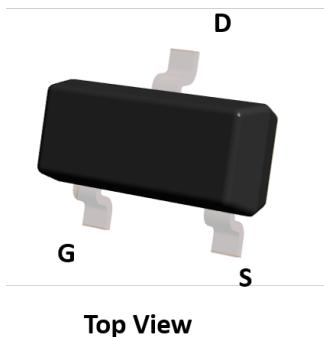
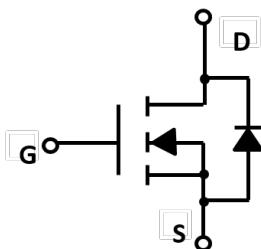


## N-Channel Enhancement Mode Field Effect Transistor


**SOT-23**


### Product Summary

- $V_{DS}$  60V
- $I_D$  340mA
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $<2.5\text{ohm}$
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ )  $<3.0\text{ohm}$

### General Description

- Trench Power MV MOSFET technology
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed
- Low Input / Output Leakage

### Applications

- Battery operated systems
- Solid-state relays
- Direct logic-level interface: TTL/CMOS

### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	60	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	$T_A=25^\circ\text{C}$ @ Steady State	$I_D$	340	mA
	$T_A=70^\circ\text{C}$ @ Steady State		272	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	1.5	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$		$P_D$	350	mW
Thermal Resistance Junction-to-Ambient @ Steady State <sup>B</sup>		$R_{\theta JA}$	357	$^\circ\text{C} / \text{W}$
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
2N7002	F2	7002.	3000	30000	120000	7" reel

■ Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS1}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
	$I_{\text{GSS2}}$	$V_{\text{GS}}= \pm 10\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 50$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=300\text{mA}$		1.2	2.5	$\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=200\text{mA}$		1.3	3.0	
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=200\text{mA}$	80			ms
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{s}}=300\text{mA}, V_{\text{GS}}=0\text{V}$			1.2	V
Maximum Body-Diode Continuous Current	$I_{\text{s}}$				340	mA
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		27.5		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			2.75		
Reverse Transfer Capacitance	$C_{\text{rss}}$			1.9		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=30\text{V}, I_{\text{D}}=0.3\text{A}$		1.6		$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$			0.47		
Gate-Drain Charge	$Q_{\text{gd}}$			0.25		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_{\text{F}}=0.3\text{A}, \text{di/dt}=-100\text{A/us}$		2.5		$\text{ns}$
Reverse Recovery Time	$t_{\text{rr}}$			11.5		
Turn-on Delay Time	$t_{\text{D(on)}}$			3.3		
Turn-on Rise Time	$t_{\text{r}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=30\text{V}, I_{\text{D}}=300\text{mA}, R_{\text{GEN}}=6\Omega$		19		$\text{ns}$
Turn-off Delay Time	$t_{\text{D(off)}}$			9.6		
Turn-off fall Time	$t_{\text{f}}$			49		

A. Pulse Test: Pulse Width  $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$ .

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## ■ Typical Performance Characteristics

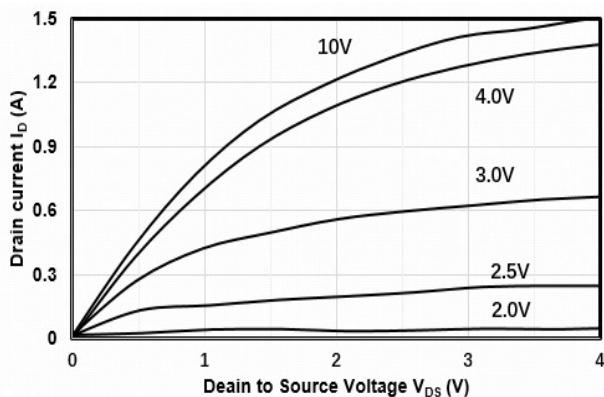


Figure1. Output Characteristics

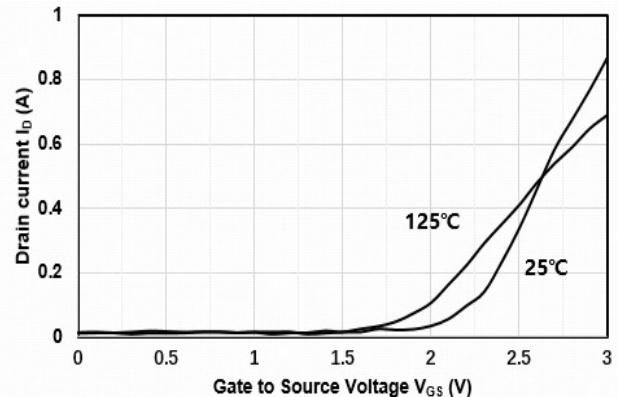


Figure2. Transfer Characteristics

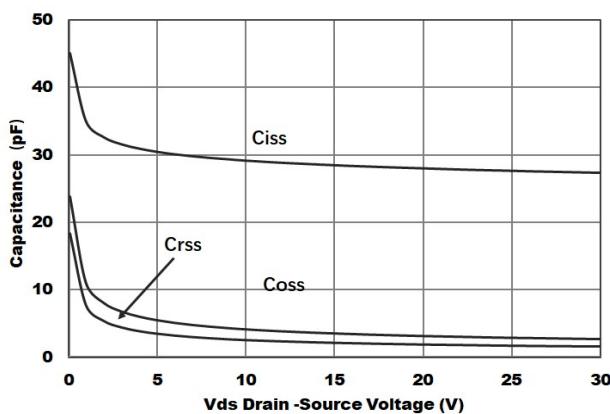


Figure3. Capacitance Characteristics

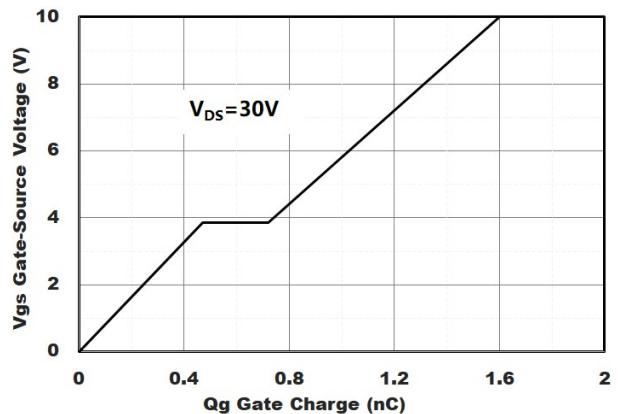


Figure4. Gate Charge

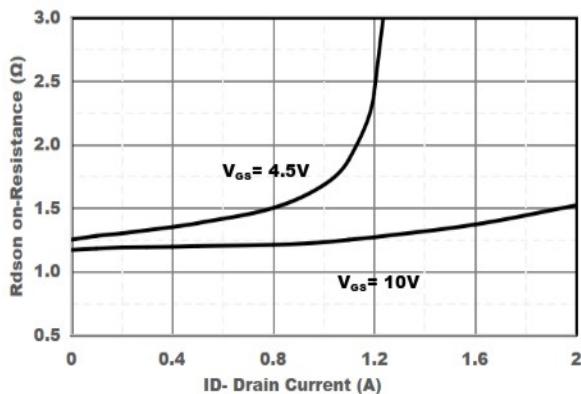


Figure5. Drain-Source on Resistance

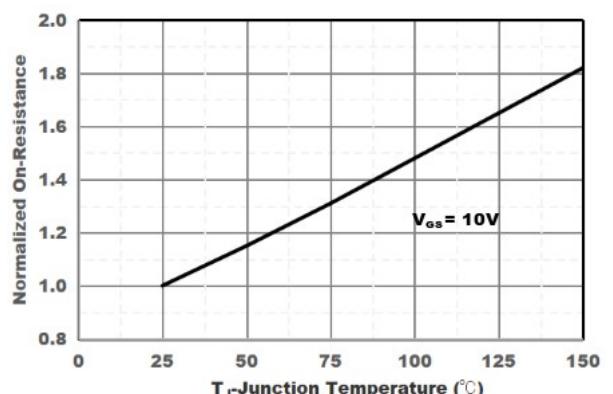


Figure6. Drain-Source on Resistance

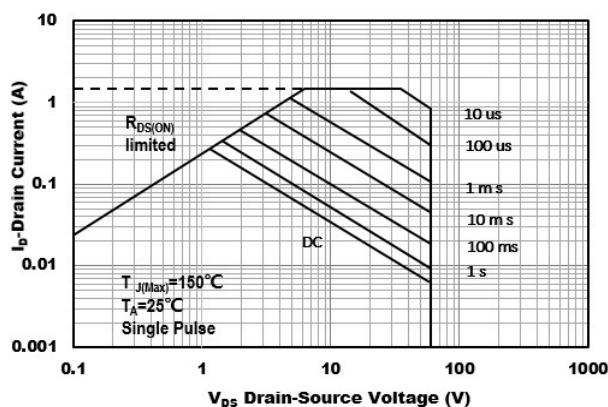


Figure7. Safe Operation Area

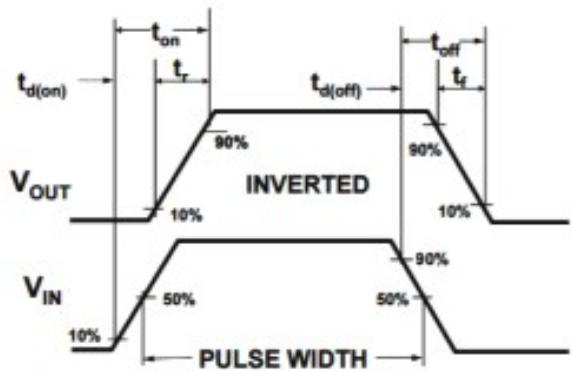
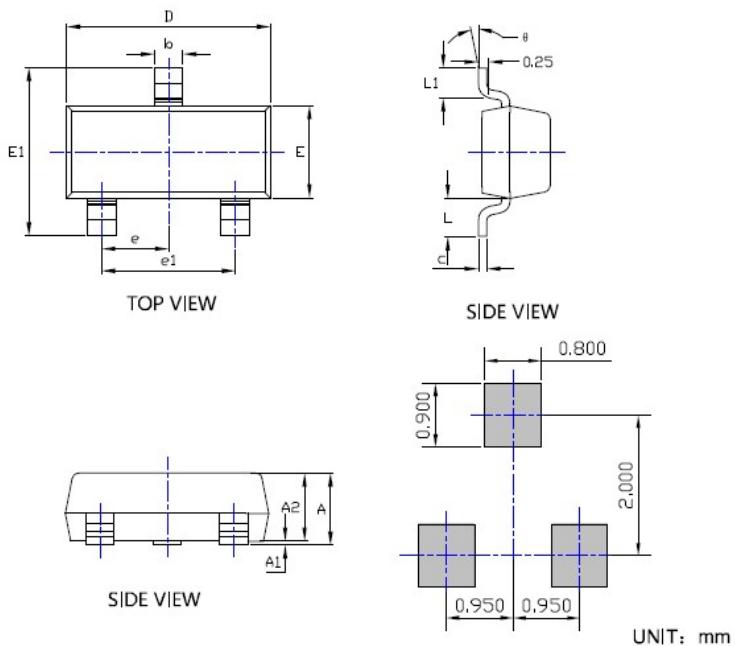


Figure8. Switching wave

### ■ SOT-23 Package information



SYMBOL	DIMENSIONS			Millimeter		
	INCHES		MIN.	NDM.	MAX.	
	MIN.	NOM.				
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037TYP	0.037TYP	0.037TYP	0.950TYP	0.950TYP	0.950TYP
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022REF		0.550REF			
L1	0.012	0.016	0.200	0.300	0.400	0.500
θ	0*	---	8*	0*	---	8*

#### NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

SUGGESTED SOLDER PAD LAYOUT